

de-panelizing scored PCBs

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- *From:* "Walter Harley" <walterh@xxxxxxxxxxxxxxxxxxxxxxxx>
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One can get PCBs manufactured as one big board that contains multiple copies of the intended product, eg an NxM array of little PCBs. The separation can either be by a v-score, or by tab-routing.

With tab-routing, it's easy to bust the individual pieces out by hand, but one is left with non-straight edges because of the spots where the tabs connect. This is fine in some applications, but a problem in applications where the board needs to butt up against eg an enclosure edge.

With v-scoring, it seems that it is physically a bit challenging to separate the boards without applying a lot of stress to the board, something I'm reluctant to do after the parts have all been soldered on.

How is separation of v-scored boards done, in commercial practice? Is there some trick to it, such as warming the board first, or using some sort of clamp?